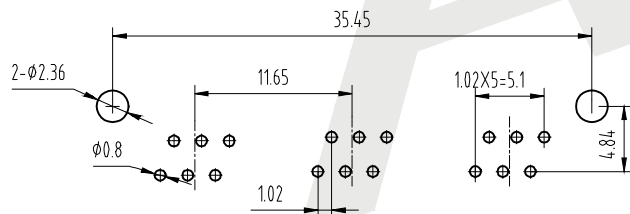
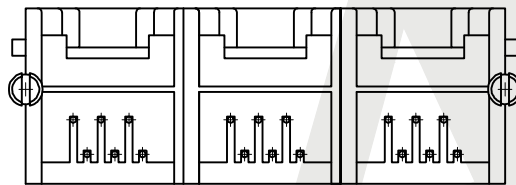
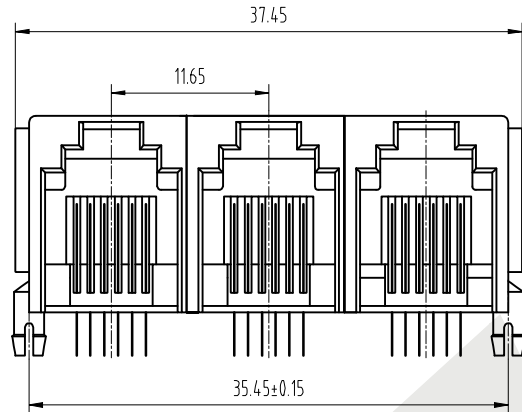
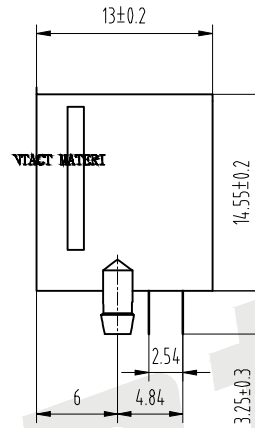


HSF



PC Board Layout
Component Side Shown



NOTES:

MATERIAL:

- 1. HOUSING MATERIAL :GLASS FILLED POYESTER UL94V-0.
- 2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.3mm
- 3. PLATING :SELECTING GOLD PLATING 1 μ ~50 μ "OVER NICKEL IN CONTACT AREA. 150 μ " TIN PLATIN.OVER NICKEL IN SOLDER AREA
- 4. SHIELD :0.2mmTHICKNESS COPPER WITH NICKEL PLATEI

ELECTRICAL

- 1. VOLTAGE RATING :125VAC RMS
- 2. CURRENT RATING :1.5AMP
- 3. CONTACT RESISTANCE:30MILLIOHMS MAX
- 4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
- 5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL

- 1. DURRABILITY :750 CYCLES MIN
- 2. PCB RETENTTON PRB-SOLDER :1 LB MIN

REVNIRONMENTAL

- 1. STORAGE :-40° C TO 85° C
- 2. OPERATION :0° C TO 70° C

Order code:

ATRJ5522 — 6P — 6C — X — A — C — A

① ② ③ ④ ⑤ ⑥ ⑦

① SERIES NO:

② NUMBER OF POSITIONS (8P,6P,4P)

③ NUMBER OF CONTACTS (8C, 6C, 4C)

④ Contact Plating

G0:GOLD flash

G1: 3U" Gold

G2: 5U" Gold

G3:10U" Gold

G4:15U" Gold

G5:30U" Gold

SN:Tin

⑤ Shield

A:W/O Shield

B:Half Shield

C:Shield W/Eml

D:Shield W/O Eml

⑥ Ports

A:1X1P

B:1X2P

C:1X3P

D:1X4P

E:1X5P

F:1X8P

⑦ With Panel or not

A:With panel

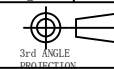
B:Without panel

Unless Otherwise specified tolerance
X. ±0.35 X.XX:±0.20
X.X:±0.25 X.XXX:±0.15

Antenk ANTENK ELECTRONICS CO.,LTD
Http://www.antenk.com
E-mail:sales@antenk.com

SCALE: As Shown UNIT: mm
DRAW Wu Sai DATE 22/03/2018
CHECK BobYang DATE 22/03/2018

TITLE: RJ11 Jack side entry,
Full Plastic 1X3P with panel



DRAWING NO: ATRJ5522-6P6C-X-A-C

PRODUCT NO: ATRJ5522-6P6C-X-A-C

REV	DESCRIPTION	DATE